

ABSTRACT

A semiconductor encapsulating epoxy resin composition comprising (A) an epoxy resin, (B) a phenolic resin curing agent, (C) a molybdenum compound, and (D) 300-900 parts by weight per 100 parts by weight of components (A) and (B) combined of an inorganic filler contains nitrogen atoms in an amount of 1.5-20% by weight based on the weight of components (A) and (B) combined. Cured parts of the composition exhibit high-temperature capabilities and flame retardance despite the absence of halogenated epoxy resins and antimony trioxide.